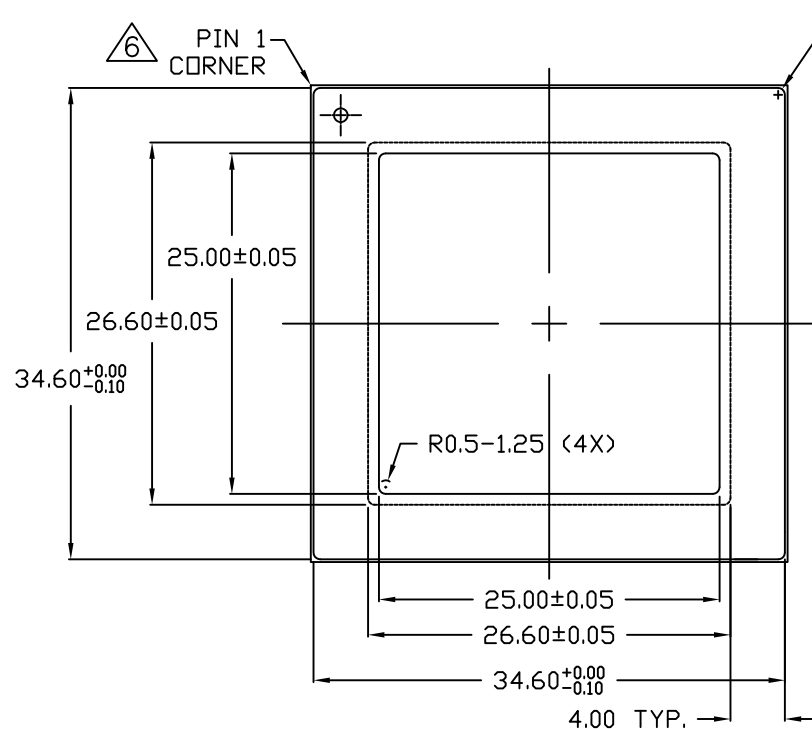
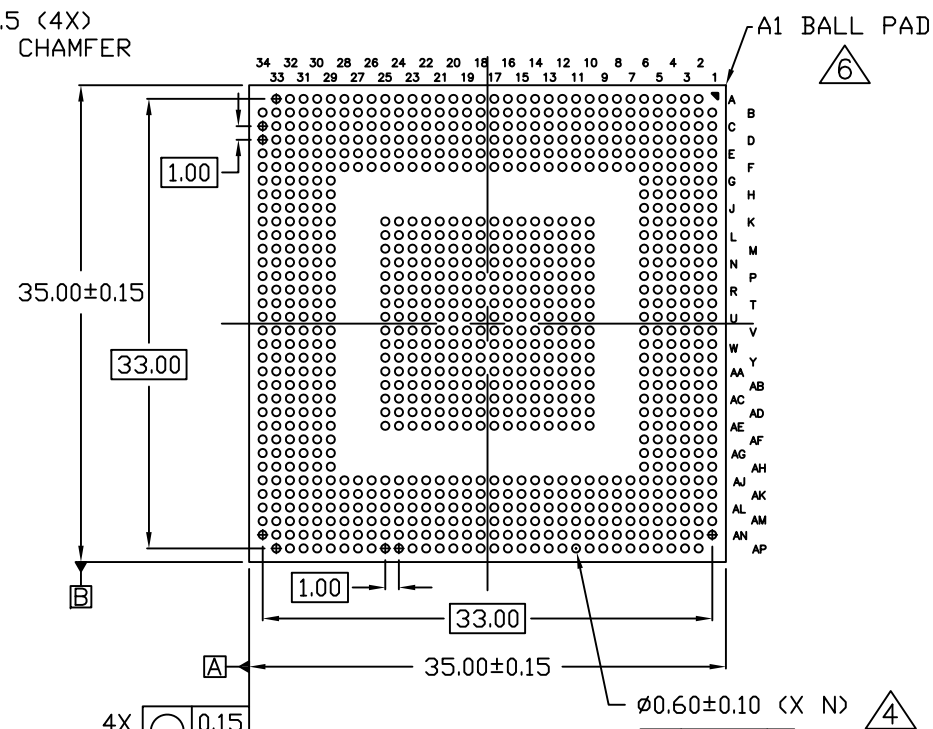
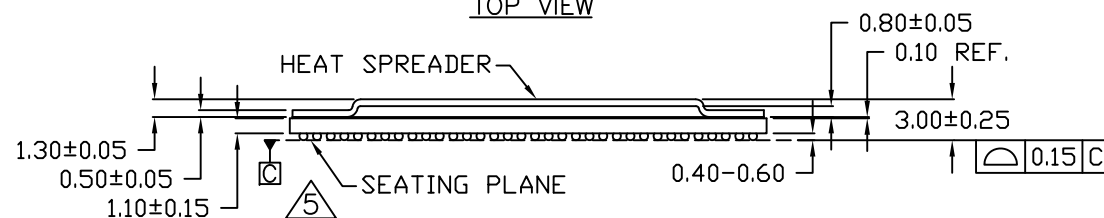




TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MATERIAL MUST BE COMPLIANT WITH MAXIM SPECIFICATION 10-0131 FOR SUBSTANCE CONTENT, MUST BE Eu ROHS COMPLIANT WITHOUT EXEMPTION AND PB-FREE.
3. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM AND BALL DIA IS 0.60 MM.
4. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM (M)
5. PRIMARY DATUM (M) AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. A1 BALL PAD CORNER I.D.
7. ALL DIMENSIONS APPLY TO LEADED (-), LEADFREE(+) AND ROHS EXEMPT (#) PKG. CODES.
8. PKG CODES: X924FH-1, X924FH-2, X924FH-3, X924FH-4, X924HF-2, X924HF-3.

-DRAWING NOT TO SCALE-



TITLE:  
PACKAGE OUTLINE, 924 BALLS HSBGAF,  
35x35x3.00mm, 1.00mm PITCH, 6 LAYERS

APPROVAL  
EDEN CHEN  
11/05/14

DOCUMENT CONTROL NO.  
21-0372

REV. 1  
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